



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Toshiya Ito

MAIL DATE CANCELED

Serial No.: 09/828,159

Group Art Unit: 2815

Filed: April 9, 2001

Examiner: Eugene Lee

For: LIGHT-EMITTING APPARATUS

Honorable Commissioner of Patents
Washington, D.C. 20231

2815
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EXCESS CLAIM FEE PAYMENT LETTER

Sir:

Transmitted herewith is an amendment in the above-identified application. The fee has been calculated and is transmitted as shown below.

	<u>AFTER AMENDMENT</u>	<u>PREV. PAID FOR</u>	<u>EXTRA CLAIMS PRESENT</u>	<u>RATE</u>	<u>FEE DUE</u>
Total Claims	25 -	20	= 5	x \$18.00	\$ 90.00
Indep. Claims	4 -	3	= 1	x \$84.00	\$ 84.00

TOTAL ADDITIONAL FEE FOR THIS AMENDMENT **\$ 174.00**

A check in the amount of \$174.00 to cover the excess claim fees is attached hereto. A duplicate copy of this sheet is enclosed. The Commissioner is authorized to charge any deficiencies in fees and credit any overpayment of fees to Attorney's Deposit Account No. 50-0481.

Respectfully Submitted,

Phillip E. Miller
Reg. No. 46,060

Date: 3/13/03

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3/31/03
Mueller

Application of

Toshiya UEMURA

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AMENDMENT UNDER 37 C.F.R. §1.111

Sir:

In response to the Office Action dated December 19, 2002, please amend the above-identified application as follows:

IN THE CLAIMS:

Please amend the claims to read as follows:

D 1
14. (Thrice Amended) A semiconductor light-emitting apparatus of a flip chip bonding type, comprising:

a transparent base comprising an inorganic material, which has on one side thereof a first bonding pad and a second bonding pad to be connected to a pair of lead frames with a space between the first and the second bonding pads where a semiconductor light-emitting element is fixed, the light-emitting element comprising:

D 2
a light-emitting layer;
a substrate disposed between said light emitting layer and said base; and
a positive electrode comprising a light non-transmissible material, said electrode being disposed on an opposite side of said light-emitting layer from said substrate and reflecting light from said light-emitting layer in a direction through said substrate and said base.

19. (Thrice Amended) A pair of lead frames for use in a light-emitting apparatus of a flip